

STGW60H65DRF

60 A, 650 V field stop trench gate IGBT with Ultrafast diode

Datasheet - production data

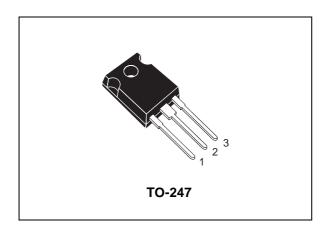
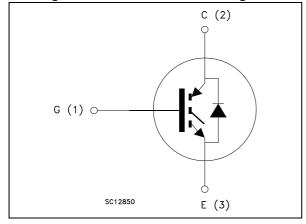


Figure 1. Internal schematic diagram



Applications

- Photovoltaic inverters
- Uninterruptible power supply
- Welding
- · Power factor correction
- High switching frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate and field stop structure. This IGBT is the result of a compromise between conduction and switching losses, maximizing the efficiency of high switching frequency converters. Furthermore, a slightly positive $V_{\text{CE}(\text{sat})}$ temperature coefficient and very tight parameter distribution result in easier paralleling operation.

Features

- · Very high speed switching
- · Tight parameters distribution
- Safe paralleling
- Low thermal resistance
- 6 µs short-circuit withstand time
- Ultrafast soft recovery antiparallel diode

Table 1. Device summary

Order code	Marking	Package	Packaging
STGW60H65DRF	GW60H65DRF	TO-247	Tube

Electrical ratings STGW60H65DRF

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CES}	Collector-emitter voltage (V _{GE} = 0)	650	V
Ic	Continuous collector current at T _C = 25 °C	120	Α
Ic	Continuous collector current at T _C = 100 °C	60	Α
I _{CP} ⁽¹⁾	Pulsed collector current	240	Α
V _{GE}	Gate-emitter voltage	±20	V
	Continuous forward current at T _C = 25 °C	120	Α
I _F	Continuous forward current at T _C = 100 °C	60	
I _{FP} ⁽¹⁾	Pulsed forward current	240	Α
P _{TOT}	Total dissipation at T _C = 25 °C	420	W
t _{SC}	Short-circuit withstand time at $V_{CC} = 400 \text{ V}$, $V_{GE} = 15 \text{ V}$	6	μs
T _{STG}	Storage temperature range	- 55 to 175	°C
T _J	Operating junction temperature	- 33 10 173	

^{1.} Pulse width limited by maximum junction temperature and turn-off within RBSOA.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.35	°C/W
R_{thJC}	Thermal resistance junction-case diode	1.38	°C/W
R _{thJA}	Thermal resistance junction-ambient	50	°C/W

2 Electrical characteristics

 $T_J = 25$ °C unless otherwise specified.

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 2 mA	650			V
	V _{CE(sat)} Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, I_{C} = 60 \text{ A}$		1.9	2.4	
VOE(+)		$V_{GE} = 15 \text{ V}, I_{C} = 60 \text{ A}$ $T_{J} = 125 \text{ °C}$		2.1		V
V _{GE(th)}	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 1 \text{ mA}$		6.0		V
I _{CES}	Collector cut-off current (V _{GE} = 0)	V _{CE} = 650 V			25	μΑ
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ± 20 V			250	nA

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	V _{CE} = 25 V, f = 1 MHz, V _{GE} = 0	-	7150 275 140	-	pF pF pF
Qg	Total gate charge		-	217	-	nC
Q _{ge}	Gate-emitter charge	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A}, V_{GE} = 15 \text{ V}$	-	67	-	nC
Q _{gc}	Gate-collector charge	GL -	-	97	-	nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$	-	85 33 1800	-	ns ns A/µs
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$ $T_{J} = 125 \text{ °C}$	-	82 35 1680	-	ns ns A/µs
t _{r(Voff)} t _{d(off)} t _f	Off voltage rise time Turn-off delay time Current fall time	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$	-	34 178 30	-	ns ns ns
$\begin{array}{c} t_{r(\text{Voff})} \\ t_{d(\text{off})} \\ t_{f} \end{array}$	Off voltage rise time Turn-off delay time Current fall time	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$ $T_{J} = 125 \text{ °C}$	-	45 205 70	-	ns ns ns

Electrical characteristics STGW60H65DRF

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E _{on} ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$	-	0.94 1.06 2.0	-	mJ mJ mJ
E _{on} ⁽¹⁾ E _{off} ⁽²⁾ E _{ts}	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V}$ $T_{J} = 125 \text{ °C}$	-	1.48 1.4 2.88	-	mJ mJ mJ

Eon is the turn-on losses when a typical diode is used in the test circuit in Figure 23. If the IGBT is offered
in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs and diode are at the
same temperature (25 °C and 125 °C).

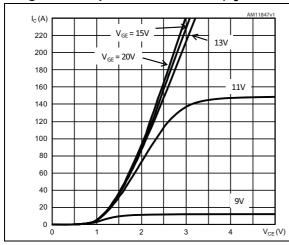
Table 8. Collector-emitter diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _F	Forward on-voltage	I _F = 60 A I _F = 60 A, T _J = 150 °C	-	3.7 2.2	4.8	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 60 \text{ A}, V_R = 400 \text{ V},$ di/dt = 1700 A/µs	-	19 200 15.5	-	ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 60 \text{ A}, V_R = 400 \text{ V},$ $di/dt = 1630 \text{ A/}\mu\text{s}$ $T_J = 125 \text{ °C}$	-	34 780 46	-	ns nC A

^{2.} Turn-off losses include also the tail of the collector current.

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics ($T_J = -40$ °C) Figure 3. Output characteristics ($T_J = 25$ °C)



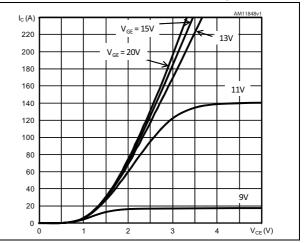


Figure 4. Output characteristics (T_J = 150 °C)

1c (A)
220
200
180
160
140
120
100
80
60
40
20
0
1 2 3 4 Vce(V)

Figure 5. Transfer characteristics

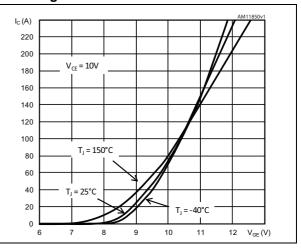


Figure 6. $V_{CE(SAT)}$ vs. junction temperature

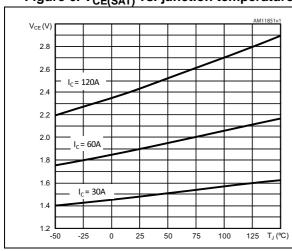
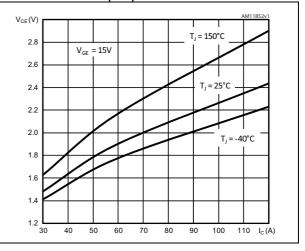


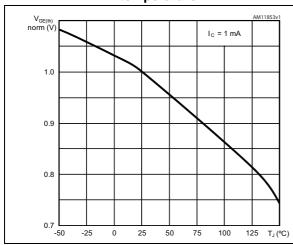
Figure 7. $V_{CE(SAT)}$ vs. collector current



Electrical characteristics STGW60H65DRF

Figure 8. Normalized V_{GE(th)} vs. junction temperature

Figure 9. Gate charge vs. gate-emitter voltage



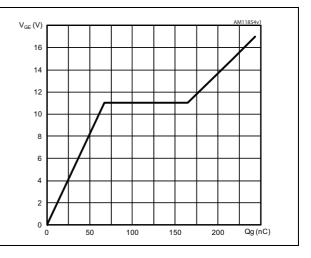
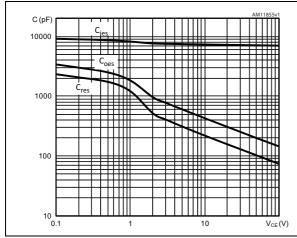


Figure 10. Capacitance variations (f = 1 MHz, $V_{GE} = 0$)

Figure 11. Switching losses vs. collector current



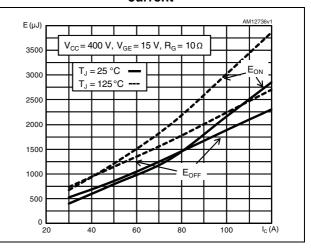
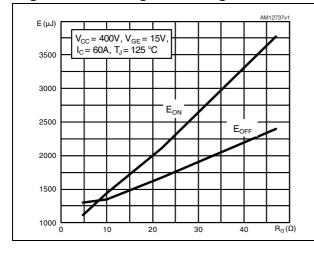
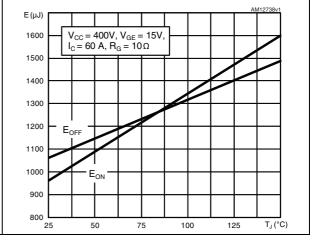


Figure 12. Switching losses vs. gate resistance

Figure 13. Switching losses vs. temperature





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Figure 14. Turn-OFF SOA

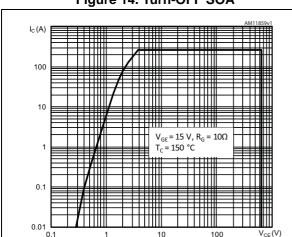


Figure 15. Short circuit time & current vs. V_{GE}

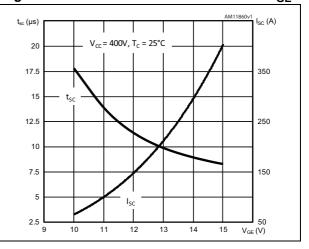
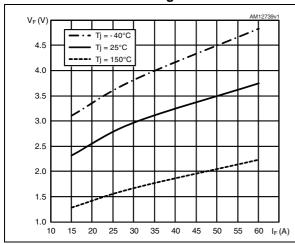


Figure 16. Diode forward current vs. forward voltage

Figure 17. Diode forward current vs. junction temperature



AM12740v1

4.5

4.0

3.5

3.0

2.5

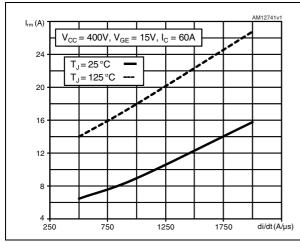
2.0

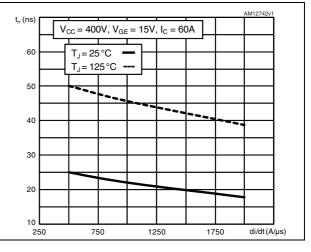
1.5

-50 -25 0 25 50 75 100 125 150 T_J (°C)

Figure 18. Reverse recovery current as a function of diode current slope

Figure 19. Reverse recovery time as a function of diode current slope

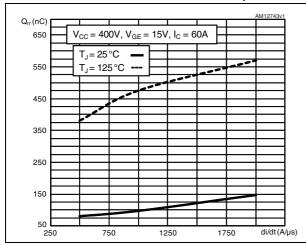




Electrical characteristics STGW60H65DRF

Figure 20. Reverse recovery charge as a function of diode current slope

Figure 21. Maximum normalized Z_{th} junction to case (IGBT)



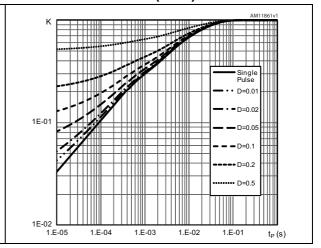
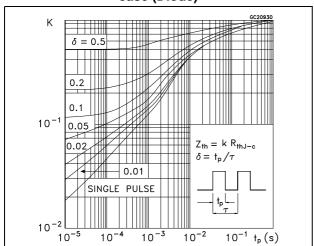


Figure 22. Maximum normalized Z_{th} junction to case (Diode)



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STGW60H65DRF Test circuits

3 Test circuits

Figure 23. Test circuit for inductive load switching

Figure 24. Gate charge test circuit

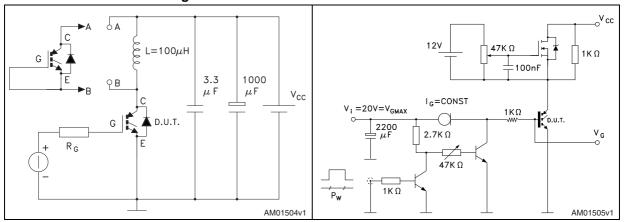
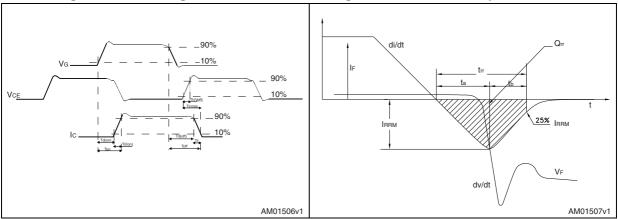


Figure 25. Switching waveform

Figure 26. Diode recovery time waveform



4 Package mechanical data

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Table 9. TO-247 mechanical data

Dim.		mm.	
Dilli.	Min.	Тур.	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
С	0.40		0.80
D	19.85		20.15
E	15.45		15.75
е	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

HEAT-SINK PLANE

BACK VIEW 0075325, G

Figure 27. TO-247 drawing

Revision history STGW60H65DRF

5 Revision history

Table 10. Document revision history

Date	Revision	Changes
11-Oct-2011	1	Initial release.
06-Jun-2012	2	Document status promoted from preliminary data production data. Added: Section 2.1: Electrical characteristics (curves) on page 5.
19-Jun-2012	3	Updated parameters in <i>Table 2</i> .
26-Jul-2012	4	Updated parameters in <i>Table 2</i> .
21-Jan-2013	5	Modified V _F test conditions, typ. and max values <i>Table 8 on page 4</i> .
02-Apr-2013	6	Modified: - P _{TOT} value <i>Table 2 on page 2</i> . - E _{on} and E _{ts} typical values <i>Table 7 on page 4</i> .

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